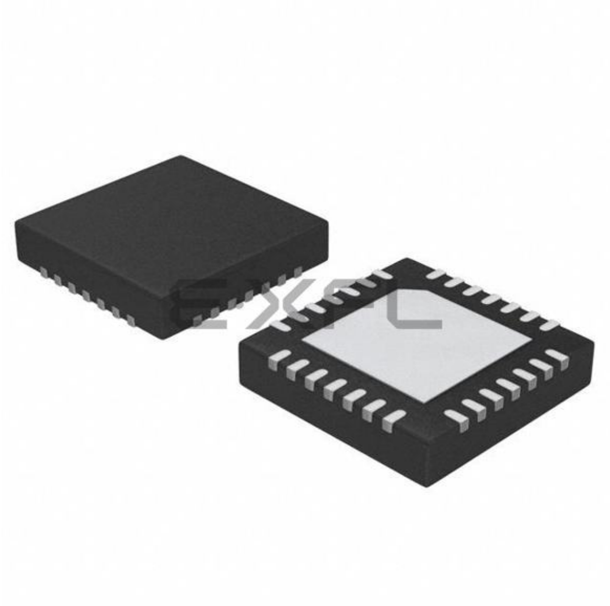
Microchip Technology - PIC24F16KL402T-I/MQ Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VFQFN Exposed Pad
Supplier Device Package	28-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16kl402t-i-mq

TABLE 1-4: PIC24F16KL40X/30X FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number				I/O	Buffer	Description
	20-Pin PDIP/ SSOP/ SOIC	20-Pin QFN	28-Pin SPDIP/ SSOP/ SOIC	28-Pin QFN			
SOSCI	9	6	11	8	I	ANA	Secondary Oscillator Input
SOSCO	10	7	12	9	O	ANA	Secondary Oscillator Output
$\overline{\text{SS1}}$	12	9	26	23	O	—	SPI1 Slave Select
$\overline{\text{SS2}}$	15	12	23	20	O	—	SPI2 Slave Select
T1CK	13	10	18	15	I	ST	Timer1 Clock
T3CK	18	15	26	23	I	ST	Timer3 Clock
T3G	6	3	6	3	I	ST	Timer3 External Gate Input
U1CTS	12	9	17	14	I	ST	UART1 Clear-to-Send Input
U1RTS	13	10	18	15	O	—	UART1 Request-to-Send Output
U1RX	6	3	6	3	I	ST	UART1 Receive
U1TX	11	8	16	13	O	—	UART1 Transmit
U2CTS	10	7	12	9	I	ST	UART2 Clear-to-Send Input
U2RTS	9	6	11	8	O	—	UART2 Request-to-Send Output
U2RX	5	2	5	2	I	ST	UART2 Receive
U2TX	4	1	4	1	O	—	UART2 Transmit
ULPWU	4	1	4	1	I	ANA	Ultra Low-Power Wake-up Input
VDD	20	17	13, 28	10, 25	P	—	Positive Supply for Peripheral Digital Logic and I/O Pins
VREF+	2	19	2	27	I	ANA	A/D Reference Voltage Input (+)
VREF-	3	20	3	28	I	ANA	A/D Reference Voltage Input (-)
VSS	19	16	8, 27	5, 24	P	—	Ground Reference for Logic and I/O Pins

Legend: TTL = TTL input buffer
ANA = Analog level input/output
ST = Schmitt Trigger input buffer
I^2C = I^2C™/SMBus input buffer

EXAMPLE 5-2: ERASING A PROGRAM MEMORY ROW – ‘C’ LANGUAGE CODE

```
// C example using MPLAB C30

  int __attribute__ ((space(auto_psv))) progAddr = &progAddr;  // Global variable located in Pgm Memory
  unsigned int offset;

//Set up pointer to the first memory location to be written

  TBLPAG = __builtin_tblpage(&progAddr);                       // Initialize PM Page Boundary SFR
  offset = &progAddr & 0xFFFF;                                 // Initialize lower word of address

  __builtin_tblwtl(offset, 0x0000);                            // Set base address of erase block
                                                               // with dummy latch write

  NVMCON = 0x4058;                                             // Initialize NVMCON

  asm("DISI #5");                                              // Block all interrupts for next 5
                                                               // instructions
  __builtin_write_NVM();                                       // C30 function to perform unlock
                                                               // sequence and set WR
```

EXAMPLE 5-3: LOADING THE WRITE BUFFERS – ASSEMBLY LANGUAGE CODE

```
; Set up NVMCON for row programming operations
       MOV     #0x4004, W0                 ;
       MOV     W0, NVMCON                  ; Initialize NVMCON
; Set up a pointer to the first program memory location to be written
; program memory selected, and writes enabled
       MOV     #0x0000, W0                 ;
       MOV     W0, TBLPAG                  ; Initialize PM Page Boundary SFR
       MOV     #0x6000, W0                 ; An example program memory address
; Perform the TBLWT instructions to write the latches
; 0th_program_word
       MOV     #LOW_WORD_0, W2             ;
       MOV     #HIGH_BYTE_0, W3            ;
       TBLWTL  W2, [W0]                    ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                  ; Write PM high byte into program latch
; 1st_program_word
       MOV     #LOW_WORD_1, W2             ;
       MOV     #HIGH_BYTE_1, W3            ;
       TBLWTL  W2, [W0]                    ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                  ; Write PM high byte into program latch
;  2nd_program_word
       MOV     #LOW_WORD_2, W2             ;
       MOV     #HIGH_BYTE_2, W3            ;
       TBLWTL  W2, [W0]                    ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                  ; Write PM high byte into program latch
       •
       •
       •
; 32nd_program_word
       MOV     #LOW_WORD_31, W2            ;
       MOV     #HIGH_BYTE_31, W3           ;
       TBLWTL  W2, [W0]                    ; Write PM low word into program latch
       TBLWTH  W3, [W0]                    ; Write PM high byte into program latch
```

6.0 DATA EEPROM MEMORY

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Data EEPROM, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Data EEPROM"** (DS39720).

The data EEPROM memory is a Nonvolatile Memory (NVM), separate from the program and volatile data RAM. Data EEPROM memory is based on the same Flash technology as program memory, and is optimized for both long retention and a higher number of erase/write cycles.

The data EEPROM is mapped to the top of the user program memory space, with the top address at program memory address, 7FFFFFh. For PIC24FXXKL4XX devices, the size of the data EEPROM is 256 words (7FFE00h to 7FFFFFh). For PIC24FXXKL3XX devices, the size of the data EEPROM is 128 words (7FFF00h to 7FFFFFh). The data EEPROM is not implemented in PIC24F08KL20X or PIC24F04KL10X devices.

The data EEPROM is organized as 16-bit wide memory. Each word is directly addressable, and is readable and writable during normal operation over the entire V_{DD} range.

Unlike the Flash program memory, normal program execution is not stopped during a data EEPROM program or erase operation.

The data EEPROM programming operations are controlled using the three NVM Control registers:

- NVMCON: Nonvolatile Memory Control Register
- NVMKEY: Nonvolatile Memory Key Register
- NVMADR: Nonvolatile Memory Address Register

6.1 NVMCON Register

The NVMCON register (Register 6-1) is also the primary control register for data EEPROM program/erase operations. The upper byte contains the control bits used to start the program or erase cycle, and the flag bit to indicate if the operation was successfully performed. The lower byte of NVMCOM configures the type of NVM operation that will be performed.

6.2 NVMKEY Register

The NVMKEY is a write-only register that is used to prevent accidental writes or erasures of data EEPROM locations.

To start any programming or erase sequence, the following instructions must be executed first, in the exact order provided:

1. Write 55h to NVMKEY.
2. Write AAh to NVMKEY.

After this sequence, a write will be allowed to the NVMCON register for one instruction cycle. In most cases, the user will simply need to set the WR bit in the NVMCON register to start the program or erase cycle. Interrupts should be disabled during the unlock sequence.

The MPLAB® C30 C compiler provides a defined library procedure (`builtin_write_NVM`) to perform the unlock sequence. Example 6-1 illustrates how the unlock sequence can be performed with in-line assembly.

EXAMPLE 6-1: DATA EEPROM UNLOCK SEQUENCE

```
//Disable Interrupts For 5 instructions
asm volatile("disi #5");
//Issue Unlock Sequence
asm volatile ("mov #0x55, W0      \n"
             "mov W0, NVMKEY      \n"
             "mov #0xAA, W1       \n"
             "mov W1, NVMKEY      \n");
// Perform Write/Erase operations
asm volatile ("bset NVMCON, #WR   \n"
             "nop                 \n"
             "nop                 \n");
```

8.0 INTERRUPT CONTROLLER

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Interrupt Controller, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Interrupts"** (DS39707).

The PIC24F interrupt controller reduces the numerous peripheral interrupt request signals to a single interrupt request signal to the CPU. It has the following features:

- Up to eight processor exceptions and software traps
- Seven user-selectable priority levels
- Interrupt Vector Table (IVT) with up to 118 vectors
- Unique vector for each interrupt or exception source
- Fixed priority within a specified user priority level
- Alternate Interrupt Vector Table (AIVT) for debug support
- Fixed interrupt entry and return latencies

8.1 Interrupt Vector Table (IVT)

The IVT is shown in Figure 8-1. The IVT resides in the program memory, starting at location, 000004h. The IVT contains 126 vectors, consisting of eight non-maskable trap vectors, plus up to 118 sources of interrupt. In general, each interrupt source has its own vector. Each interrupt vector contains a 24-bit wide address. The value programmed into each interrupt vector location is the starting address of the associated Interrupt Service Routine (ISR).

Interrupt vectors are prioritized in terms of their natural priority; this is linked to their position in the vector table. All other things being equal, lower addresses have a higher natural priority. For example, the interrupt associated with vector 0 will take priority over interrupts at any other vector address.

PIC24F16KL402 family devices implement 32 non-maskable traps and unique interrupts; these are summarized in Table 8-1 and Table 8-2.

8.1.1 ALTERNATE INTERRUPT VECTOR TABLE (AIVT)

The Alternate Interrupt Vector Table (AIVT) is located after the IVT, as shown in Figure 8-1. Access to the AIVT is provided by the ALTIVT control bit (INTCON2<15>). If the ALTIVT bit is set, all interrupt and exception processes will use the alternate vectors instead of the default vectors. The alternate vectors are organized in the same manner as the default vectors.

The AIVT supports emulation and debugging efforts by providing a means to switch between an application and a support environment without requiring the interrupt vectors to be reprogrammed. This feature also enables switching between applications for evaluation of different software algorithms at run time. If the AIVT is not needed, the AIVT should be programmed with the same addresses used in the IVT.

8.2 Reset Sequence

A device Reset is not a true exception, because the interrupt controller is not involved in the Reset process. The PIC24F devices clear their registers in response to a Reset, which forces the Program Counter (PC) to zero. The microcontroller then begins program execution at location, 000000h. The user programs a `GOTO` instruction at the Reset address, which redirects the program execution to the appropriate start-up routine.

Note:	Any unimplemented or unused vector locations in the IVT and AIVT should be programmed with the address of a default interrupt handler routine that contains a `RESET` instruction.

REGISTER 8-1: SR: ALU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	DC[1]
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2[2,3]	IPL1[2,3]	IPL0[2,3]	RA[1]	N[1]	OV[1]	Z[1]	C[1]
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘`0`’

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits[2,3]

`111` = CPU Interrupt Priority Level is 7 (15); user interrupts disabled
`110` = CPU Interrupt Priority Level is 6 (14)
`101` = CPU Interrupt Priority Level is 5 (13)
`100` = CPU Interrupt Priority Level is 4 (12)
`011` = CPU Interrupt Priority Level is 3 (11)
`010` = CPU Interrupt Priority Level is 2 (10)
`001` = CPU Interrupt Priority Level is 1 (9)
`000` = CPU Interrupt Priority Level is 0 (8)

Note 1: See Register 3-1 for the description of these bits, which are not dedicated to interrupt control functions.

2: The IPL bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the Interrupt Priority Level if IPL3 = `1`.

3: The IPL Status bits are read-only when NSTDIS (INTCON1<15>) = `1`.

Note: Bit 8 and bits 4 through 0 are described in **Section 3.0 “CPU”**.

REGISTER 9-4: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROEN	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ROEN:** Reference Oscillator Output Enable bit

`1` = Reference oscillator is enabled on REFO pin
`0` = Reference oscillator is disabled

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **ROSSLP:** Reference Oscillator Output Stop in Sleep bit

`1` = Reference oscillator continues to run in Sleep
`0` = Reference oscillator is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit

`1` = Primary oscillator is used as the base clock[1]
`0` = System clock is used as the base clock; the base clock reflects any clock switching of the device

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divisor Select bits

`1111` = Base clock value divided by 32,768
`1110` = Base clock value divided by 16,384
`1101` = Base clock value divided by 8,192
`1100` = Base clock value divided by 4,096
`1011` = Base clock value divided by 2,048
`1010` = Base clock value divided by 1,024
`1001` = Base clock value divided by 512
`1000` = Base clock value divided by 256
`0111` = Base clock value divided by 128
`0110` = Base clock value divided by 64
`0101` = Base clock value divided by 32
`0100` = Base clock value divided by 16
`0011` = Base clock value divided by 8
`0010` = Base clock value divided by 4
`0001` = Base clock value divided by 2
`0000` = Base clock value

bit 7-0 **Unimplemented:** Read as ‘`0`’

Note 1: The crystal oscillator must be enabled using the FOSC<2:0> bits; the crystal maintains the operation in Sleep mode.

10.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Power-Saving Features, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Power-Saving Features with Deep Sleep"** (DS39727).

The PIC24F16KL402 family of devices provides the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. All PIC24F devices manage power consumption using several strategies:

- Clock frequency
- Instruction-based Idle and Sleep modes
- Hardware-based periodic wake-up from Sleep
- Software Controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption, while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

PIC24F devices allow for a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits. The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

PIC24F devices have two special power-saving modes that are entered through the execution of a special `PWRSAV` instruction. Sleep mode stops clock operation and halts all code execution; Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation.

The assembly syntax of the `PWRSAV` instruction is shown in Example 10-1.

Note: `SLEEP_MODE` and `IDLE_MODE` are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

EXAMPLE 10-1: `PWRSAV` INSTRUCTION SYNTAX

```
PWRSAV     #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV     #IDLE_MODE     ; Put the device into IDLE mode
```

REGISTER 16-3: ECCP1AS: ECCP1 AUTO-SHUTDOWN CONTROL REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ECCPASE	ECCPAS2	ECCPAS1	ECCPAS0	PSSAC1	PSSAC0	PSSBD1	PSSBD0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8	**Unimplemented:** Read as ‘0’
bit 7	**ECCPASE:** ECCP1 Auto-Shutdown Event Status bit 1 = A shutdown event has occurred; ECCP outputs are in a shutdown state 0 = ECCP outputs are operating
bit 6-4	**ECCPAS<2:0>:** ECCP1 Auto-Shutdown Source Select bits 111 = V_{IL} on $\overline{\text{FLT0}}$ pin, or either C1OUT or C2OUT is high 110 = V_{IL} on $\overline{\text{FLT0}}$ pin or C2OUT comparator output is high 101 = V_{IL} on $\overline{\text{FLT0}}$ pin or C1OUT comparator output is high 100 = V_{IL} on $\overline{\text{FLT0}}$ pin 011 = Either C1OUT or C2OUT is high 010 = C2OUT comparator output is high 001 = C1OUT comparator output is high 000 = Auto-shutdown is disabled
bit 3-2	**PSSAC<1:0>:** P1A and P1C Pins Shutdown State Control bits 1x = P1A and P1C pins tri-state 01 = Drive pins, P1A and P1C, to ‘1’ 00 = Drive pins, P1A and P1C, to ‘0’
bit 1-0	**PSSBD<1:0>:** P1B and P1D Pins Shutdown State Control bits 1x = P1B and P1D pins tri-state 01 = Drive pins, P1B and P1D, to ‘1’ 00 = Drive pins, P1B and P1D, to ‘0’

Note 1: This register is implemented only on PIC24FXXKL40X/30X devices.

Note 1: The auto-shutdown condition is a level-based signal, not an edge-based signal. As long as the level is present, the auto-shutdown will persist.

2: Writing to the ECCPASE bit is disabled while an auto-shutdown condition persists.

3: Once the auto-shutdown condition has been removed and the PWM restarted (either through firmware or auto-restart), the PWM signal will always restart at the beginning of the next PWM period.

REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)

bit 5	**ADDEN:** Address Character Detect bit (bit 8 of the received data = `1`) `1` = Address Detect mode is enabled; if 9-bit mode is not selected, this does not take effect `0` = Address Detect mode is disabled
bit 4	**RIDLE:** Receiver Idle bit (read-only) `1` = Receiver is Idle `0` = Receiver is active
bit 3	**PERR:** Parity Error Status bit (read-only) `1` = Parity error has been detected for the current character (character at the top of the receive FIFO) `0` = Parity error has not been detected
bit 2	**FERR:** Framing Error Status bit (read-only) `1` = Framing error has been detected for the current character (character at the top of the receive FIFO) `0` = Framing error has not been detected
bit 1	**OERR:** Receive Buffer Overrun Error Status bit (clear/read-only) `1` = Receive buffer has overflowed `0` = Receive buffer has not overflowed (clearing a previously set OERR bit (`1` → `0` transition) will reset the receiver buffer and the RSR to the empty state)
bit 0	**URXDA:** UARTx Receive Buffer Data Available bit (read-only) `1` = Receive buffer has data; at least one more character can be read `0` = Receive buffer is empty

19.0 10-BIT HIGH-SPEED A/D CONVERTER

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the 10-Bit High-Speed A/D Converter, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"10-Bit A/D Converter"** (DS39705).

The 10-bit A/D Converter has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 500 ksps
- Up to 12 analog input pins
- External voltage reference input pins
- Internal band gap reference input
- Automatic Channel Scan mode
- Selectable conversion trigger source
- Two-word conversion result buffer
- Selectable Buffer Fill modes
- Four result alignment options
- Operation during CPU Sleep and Idle modes

Depending on the particular device, PIC24F16KL402 family devices implement up to 12 analog input pins, designated AN0 through AN4 and AN9 through AN15. In addition, there are two analog input pins for external voltage reference connections (VREF+ and VREF-). These voltage reference inputs may be shared with other analog input pins.

A block diagram of the A/D Converter is displayed in Figure 19-1.

To perform an A/D conversion:

1. Configure the A/D module:
   a) Configure port pins as analog inputs and/ or select band gap reference inputs (ANSA<3:0>, ANSB<15:12,4:0> and ANCFG<0>).
   b) Select the voltage reference source to match the expected range on analog inputs (AD1CON2<15:13>).
   c) Select the analog conversion clock to match the desired data rate with the processor clock (AD1CON3<7:0>).
   d) Select the appropriate sample/conversion sequence (AD1CON1<7:5> and AD1CON3<12:8>).
   e) Select how conversion results are presented in the buffer (AD1CON1<9:8>).
   f) Select interrupt rate (AD1CON2<5:2>).
   g) Turn on A/D module (AD1CON1<15>).
2. Configure A/D interrupt (if required):
   a) Clear the AD1IF bit.
   b) Select A/D interrupt priority.

22.0 HIGH/LOW-VOLTAGE DETECT (HLVD)

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the High/Low-Voltage Detect, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"High-Level Integration with Programmable High/Low-Voltage Detect (HLVD)"** (DS39725).

The High/Low-Voltage Detect module (HLVD) is a programmable circuit that allows the user to specify both the device voltage trip point and the direction of change.

An interrupt flag is set if the device experiences an excursion past the trip point in the direction of change. If the interrupt is enabled, the program execution will branch to the interrupt vector address and the software can then respond to the interrupt.

The HLVD Control register (see Register 22-1) completely controls the operation of the HLVD module. This allows the circuitry to be "turned off" by the user under software control, which minimizes the current consumption for the device.

FIGURE 22-1: HIGH/LOW-VOLTAGE DETECT (HLVD) MODULE BLOCK DIAGRAM

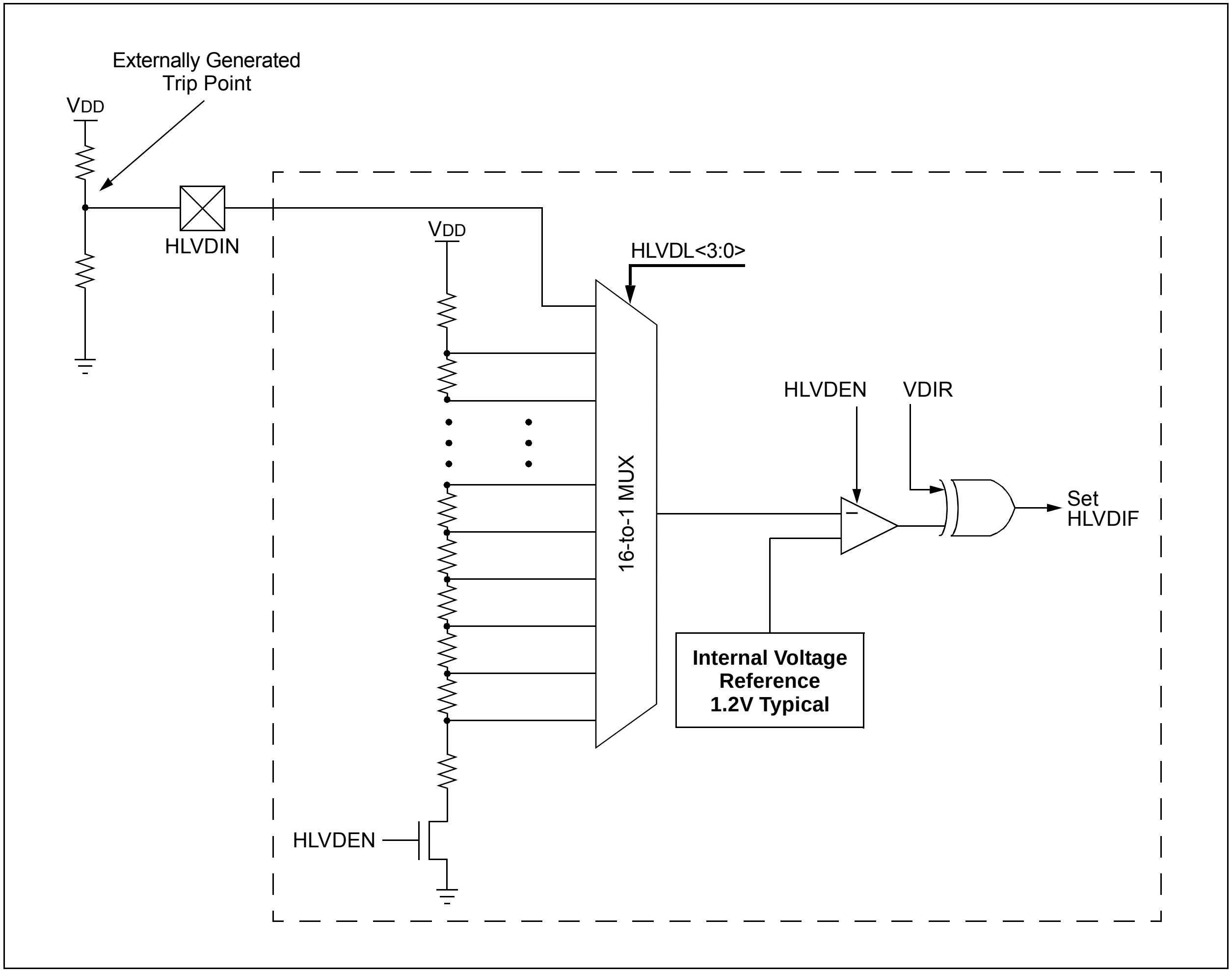
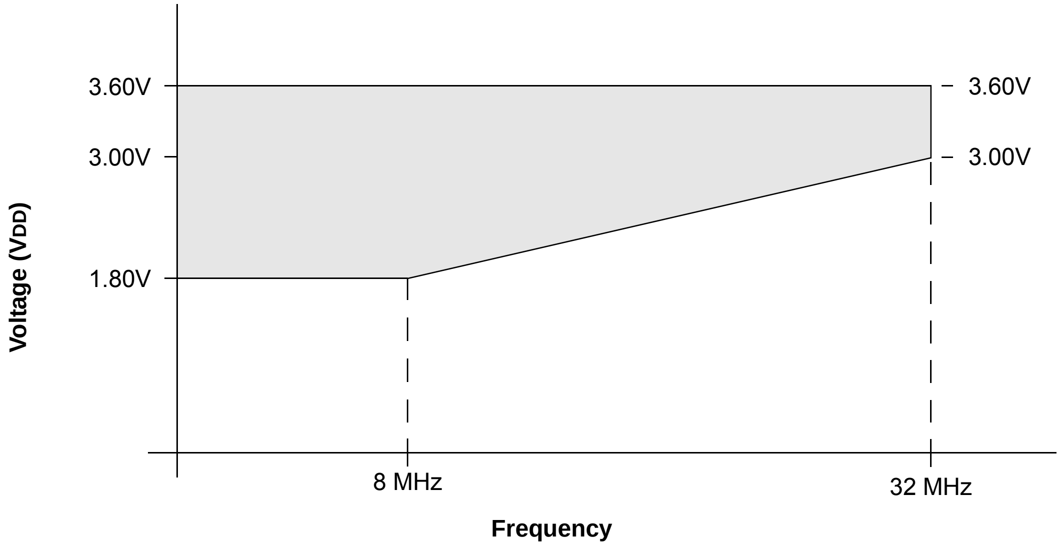


TABLE 25-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
GOTO	GOTO	Expr	Go to Address	2	2	None
	GOTO	Wn	Go to Indirect	1	2	None
INC	INC	f	f = f + 1	1	1	C, DC, N, OV, Z
	INC	f,WREG	WREG = f + 1	1	1	C, DC, N, OV, Z
	INC	Ws,Wd	Wd = Ws + 1	1	1	C, DC, N, OV, Z
INC2	INC2	f	f = f + 2	1	1	C, DC, N, OV, Z
	INC2	f,WREG	WREG = f + 2	1	1	C, DC, N, OV, Z
	INC2	Ws,Wd	Wd = Ws + 2	1	1	C, DC, N, OV, Z
IOR	IOR	f	f = f .IOR. WREG	1	1	N, Z
	IOR	f,WREG	WREG = f .IOR. WREG	1	1	N, Z
	IOR	#lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N, Z
	IOR	Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N, Z
	IOR	Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N, Z
LNK	LNK	#lit14	Link Frame Pointer	1	1	None
LSR	LSR	f	f = Logical Right Shift f	1	1	C, N, OV, Z
	LSR	f,WREG	WREG = Logical Right Shift f	1	1	C, N, OV, Z
	LSR	Ws,Wd	Wd = Logical Right Shift Ws	1	1	C, N, OV, Z
	LSR	Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N, Z
	LSR	Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N, Z
MOV	MOV	f,Wn	Move f to Wn	1	1	None
	MOV	[Wns+Slit10],Wnd	Move [Wns+Slit10] to Wnd	1	1	None
	MOV	f	Move f to f	1	1	N, Z
	MOV	f,WREG	Move f to WREG	1	1	None
	MOV	#lit16,Wn	Move 16-bit Literal to Wn	1	1	None
	MOV.b	#lit8,Wn	Move 8-bit Literal to Wn	1	1	None
	MOV	Wn,f	Move Wn to f	1	1	None
	MOV	Wns,[Wns+Slit10]	Move Wns to [Wns+Slit10]	1	1	None
	MOV	Wso,Wdo	Move Ws to Wd	1	1	None
	MOV	WREG,f	Move WREG to f	1	1	None
	MOV.D	Wns,Wd	Move Double from W(ns):W(ns+1) to Wd	1	2	None
	MOV.D	Ws,Wnd	Move Double from Ws to W(nd+1):W(nd)	1	2	None
MUL	MUL.SS	Wb,Ws,Wnd	{Wnd+1, Wnd} = Signed(Wb) * Signed(Ws)	1	1	None
	MUL.SU	Wb,Ws,Wnd	{Wnd+1, Wnd} = Signed(Wb) * Unsigned(Ws)	1	1	None
	MUL.US	Wb,Ws,Wnd	{Wnd+1, Wnd} = Unsigned(Wb) * Signed(Ws)	1	1	None
	MUL.UU	Wb,Ws,Wnd	{Wnd+1, Wnd} = Unsigned(Wb) * Unsigned(Ws)	1	1	None
	MUL.SU	Wb,#lit5,Wnd	{Wnd+1, Wnd} = Signed(Wb) * Unsigned(lit5)	1	1	None
	MUL.UU	Wb,#lit5,Wnd	{Wnd+1, Wnd} = Unsigned(Wb) * Unsigned(lit5)	1	1	None
	MUL	f	W3:W2 = f * WREG	1	1	None
NEG	NEG	f	f = $\overline{f}$ + 1	1	1	C, DC, N, OV, Z
	NEG	f,WREG	WREG = $\overline{f}$ + 1	1	1	C, DC, N, OV, Z
	NEG	Ws,Wd	Wd = $\overline{Ws}$ + 1	1	1	C, DC, N, OV, Z
NOP	NOP		No Operation	1	1	None
	NOPR		No Operation	1	1	None
POP	POP	f	Pop f from Top-of-Stack (TOS)	1	1	None
	POP	Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
	POP.D	Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd+1)	1	2	None
	POP.S		Pop Shadow Registers	1	1	All
PUSH	PUSH	f	Push f to Top-of-Stack (TOS)	1	1	None
	PUSH	Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
	PUSH.D	Wns	Push W(ns):W(ns+1) to Top-of-Stack (TOS)	1	2	None
	PUSH.S		Push Shadow Registers	1	1	None

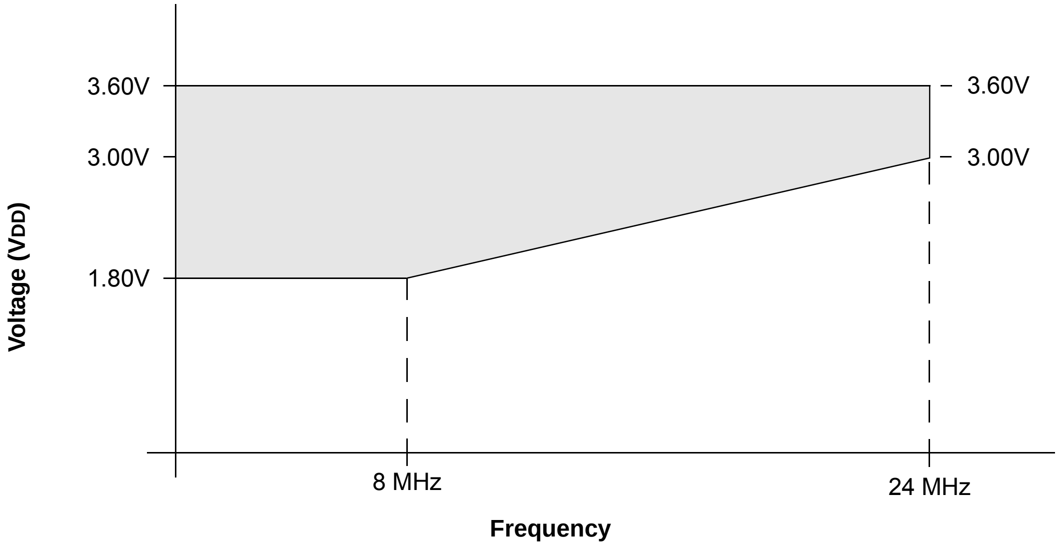
26.1 DC Characteristics

FIGURE 26-1: PIC24F16KL402 FAMILY VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



Note: For frequencies between 8 MHz and 32 MHz, F_{MAX} = 20 MHz * (V_{DD} – 1.8) + 8 MHz.

FIGURE 26-2: PIC24F16KL402 FAMILY VOLTAGE-FREQUENCY GRAPH (EXTENDED)



Note: For frequencies between 8 MHz and 24 MHz, F_{MAX} = 13.33 MHz * (V_{DD} – 1.8) + 8 MHz.

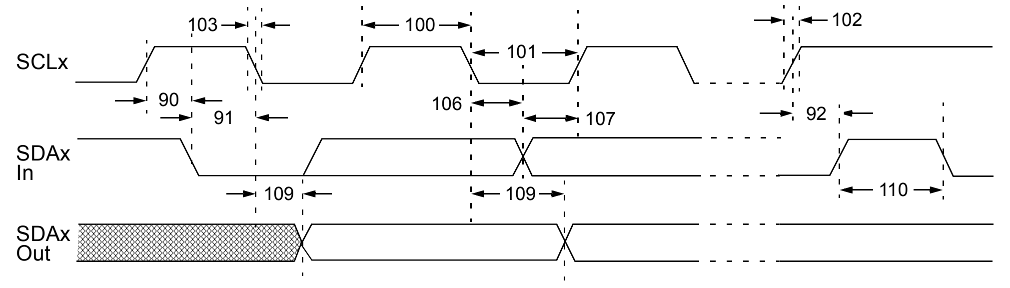
TABLE 26-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical[1]**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)						
DC60	0.01	0.20	μA	-40°C	1.8V	Sleep Mode[2]
	0.03	0.20	μA	+25°C		
	0.06	0.87	μA	+60°C		
	0.20	1.35	μA	+85°C		
	—	8.00	μA	+125ºC		
	0.01	0.54	μA	-40°C	3.3V	
	0.03	0.54	μA	+25°C		
	0.08	1.68	μA	+60°C		
	0.25	2.45	μA	+85°C		
	—	10.00	μA	+125ºC		

Note 1: Data in the Typical column is at 3.3V, +25°C unless otherwise stated.

2: Base IPD is measured with all peripherals and clocks disabled. All I/Os are configured as outputs and set low; PMDx bits are set to '1' and WDT, etc., are all disabled

FIGURE 26-14: MSSPx I^2C™ BUS DATA TIMING



Note: Refer to Figure 26-3 for load conditions.

TABLE 26-34: I^2C™ BUS DATA REQUIREMENTS (MASTER MODE)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
101	TLOW	Clock Low Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
102	TR	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
103	TF	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
90	TSU:STA	Start Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	Only relevant for Repeated Start condition
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
91	THD:STA	Start Condition Hold Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	After this period, the first clock pulse is generated
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 1)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	—	
			400 kHz mode	2(TOSC)(BRG + 1)	—	—	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
D102	CB	Bus Capacitive Loading		—	400	pF	

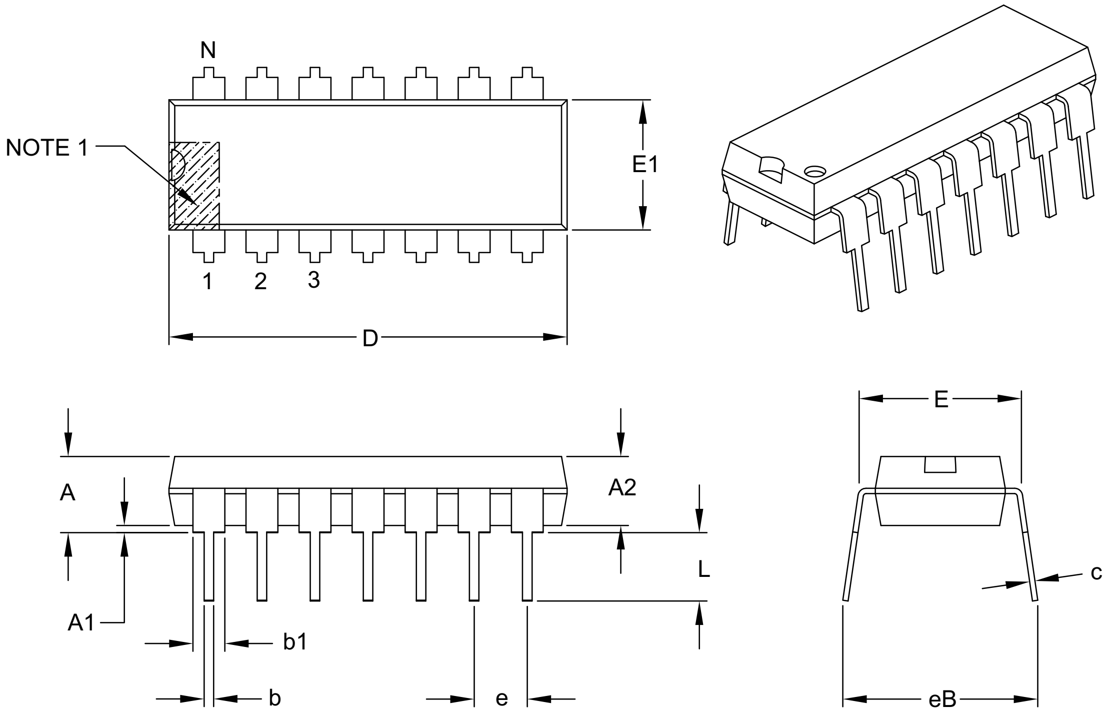
Note 1: A Fast mode I^2C bus device can be used in a Standard mode I^2C bus system, but Parameter 107 $\geq$ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCLx signal. If such a device does stretch the LOW period of the SCLx signal, it must output the next data bit to the SDAx line, Parameter 102 + Parameter 107 = 1000 + 250 = 1250 ns (for 100 kHz mode), before the SCLx line is released.

27.2 Package Details

The following sections give the technical details of the packages.

14-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.735	.750	.775
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

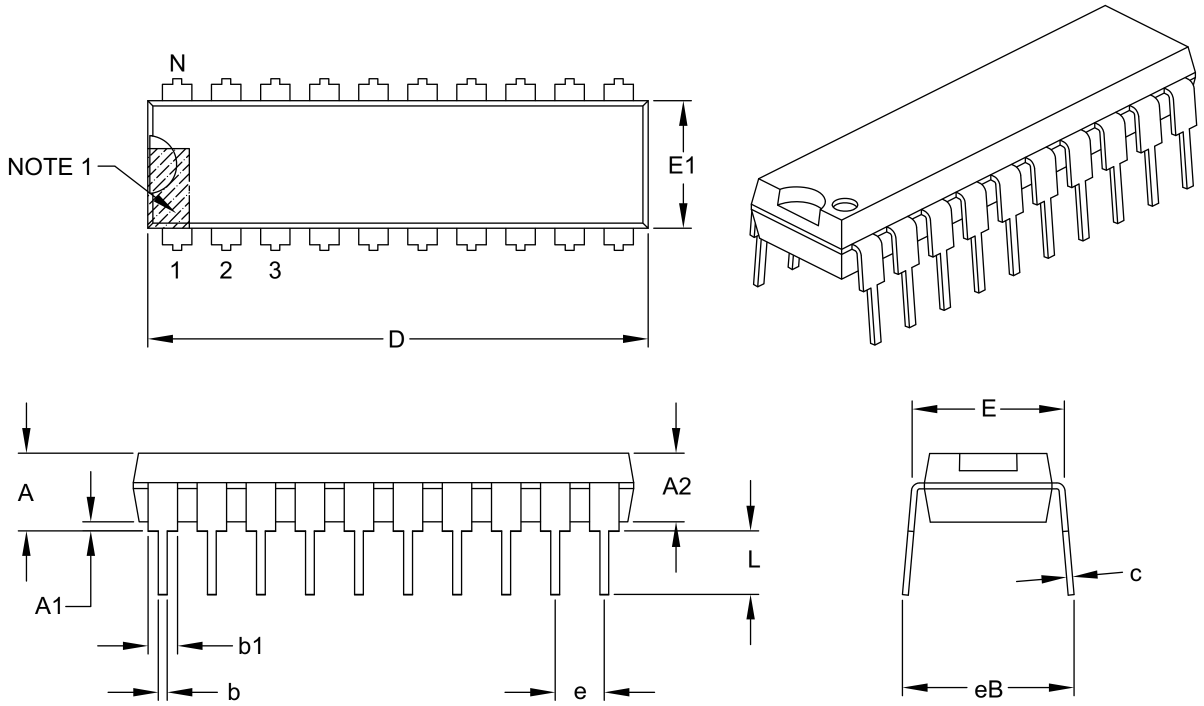
1. Pin 1 visual index feature may vary, but must be located with the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-005B

20-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES		
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.980	1.030	1.060
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

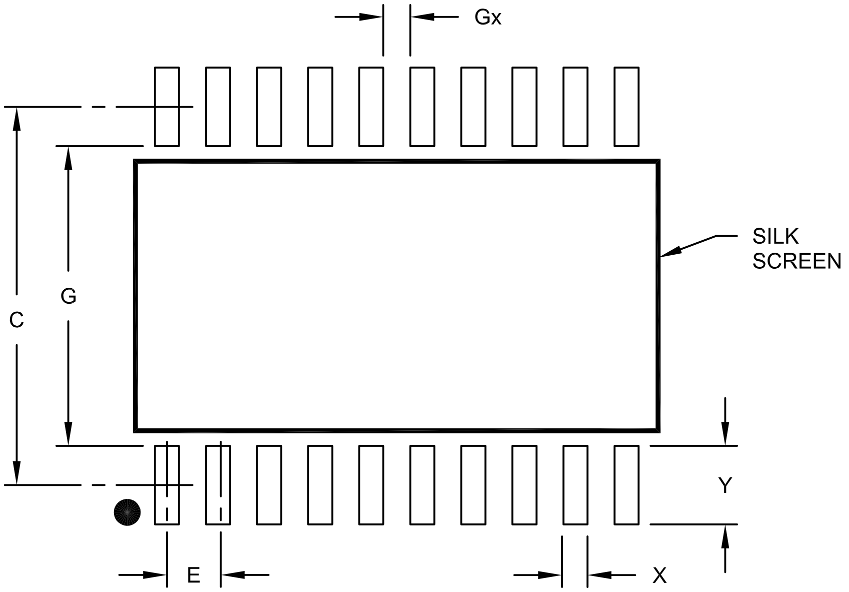
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-019B

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X20)	X			0.60
Contact Pad Length (X20)	Y			1.95
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.45		

Notes:

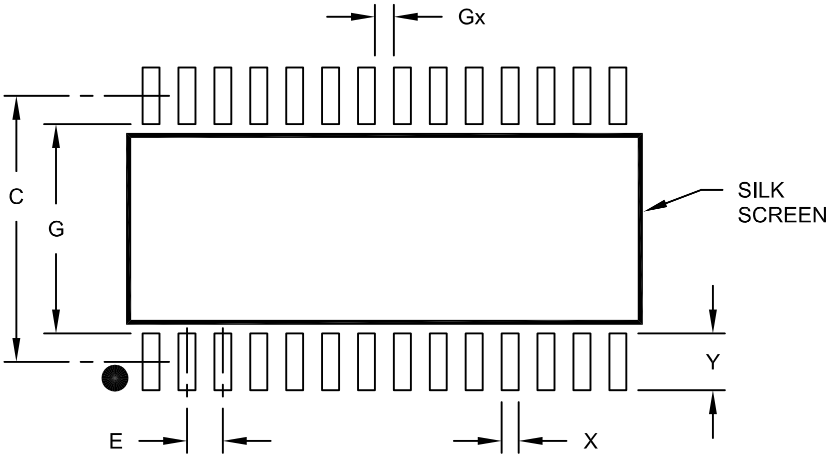
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2094A

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

NOTES: